

**POLISHING PAD, MANUFACTURING METHOD THEREOF AND
PREPARING METHOD OF SEMICONDUCTOR DEVICE USING THE SAME**

ABSTRACT

5 The present disclosure relates to a polishing pad, a method of manufacturing the
polishing pad, and a method of manufacturing a semiconductor device using the same.
In the polishing pad, an unexpanded solid-phase blowing agent is included in a polishing
composition when a polishing layer is manufactured, and the unexpanded solid-phase
blowing agent is expanded during a curing process to form a plurality of uniform pores
10 in the polishing layer, such that defects occurring on a surface of the semiconductor
substrate may be prevented. In addition, the present disclosure may provide a method of
manufacturing a semiconductor device to which the polishing pad is applied.

Fig. 3